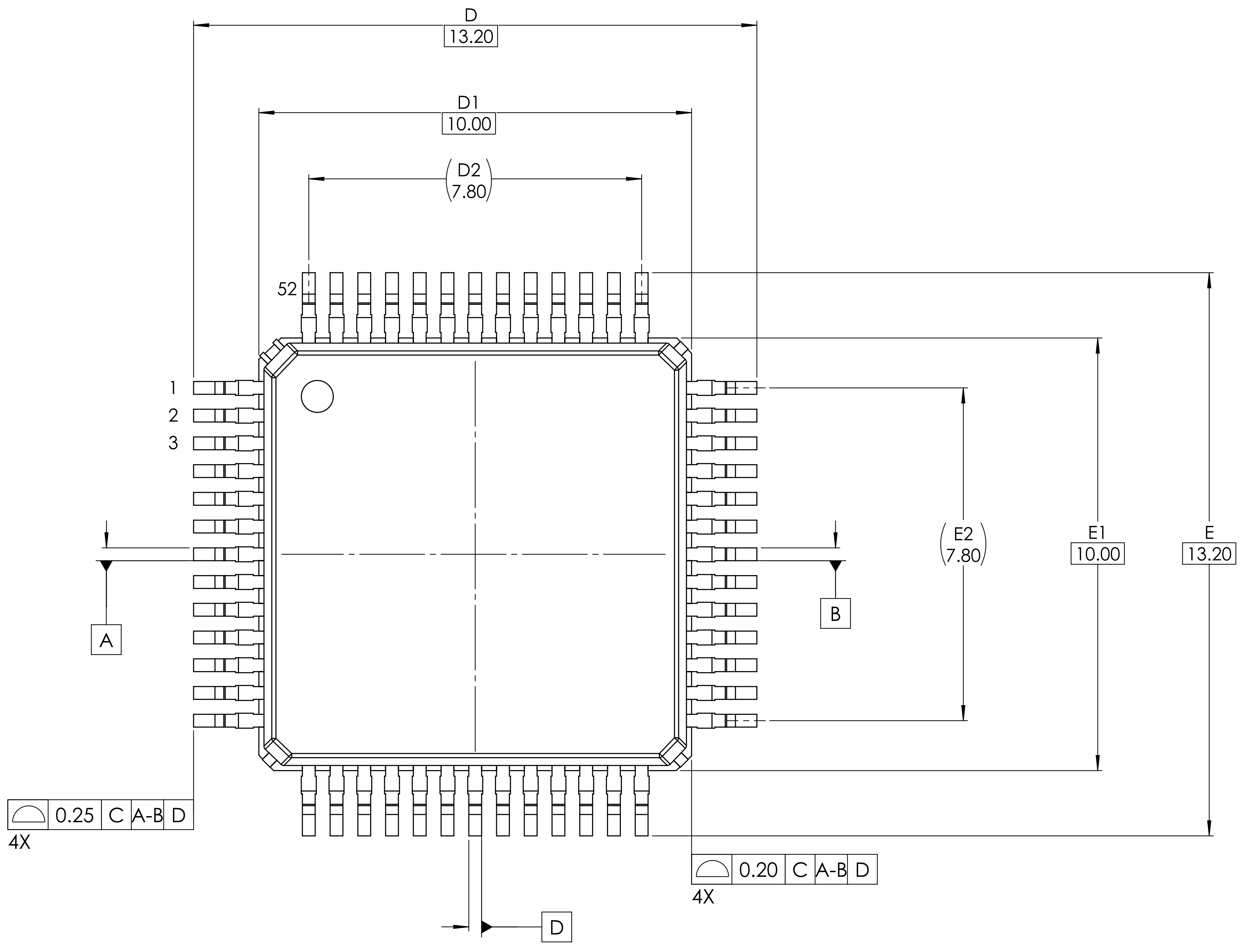
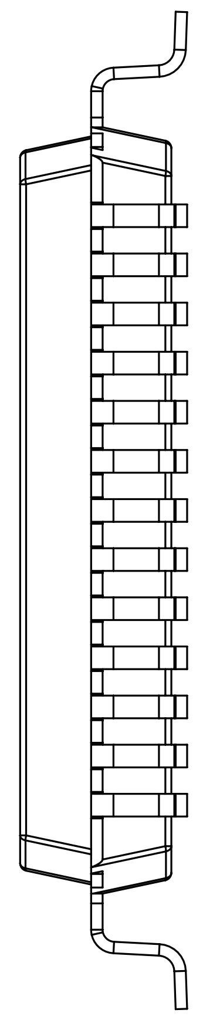
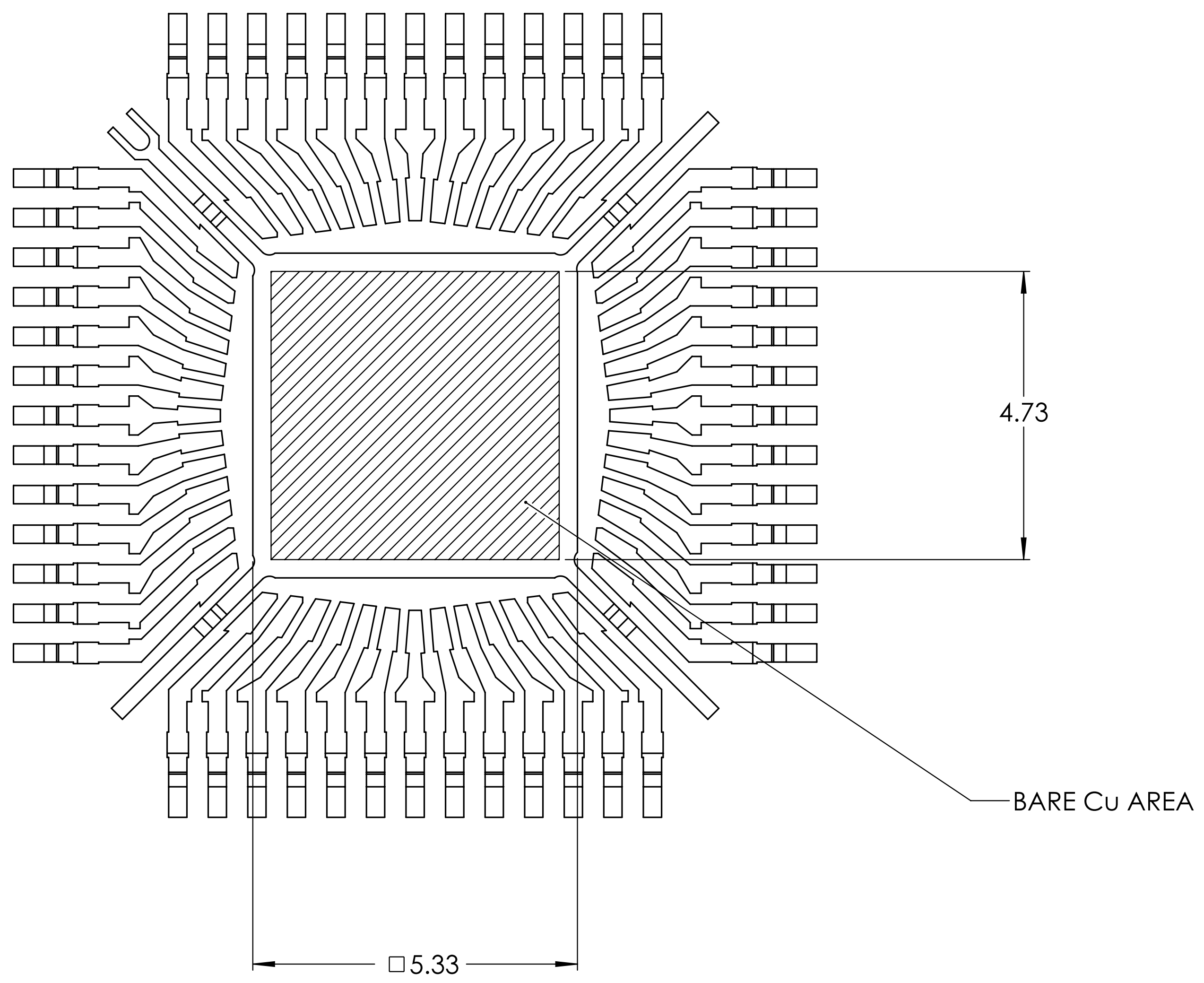
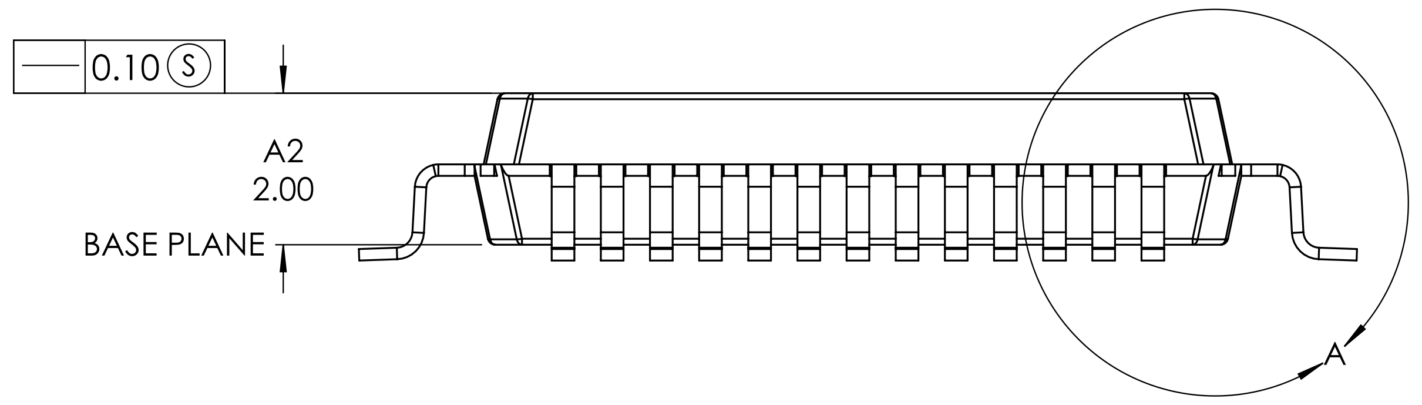
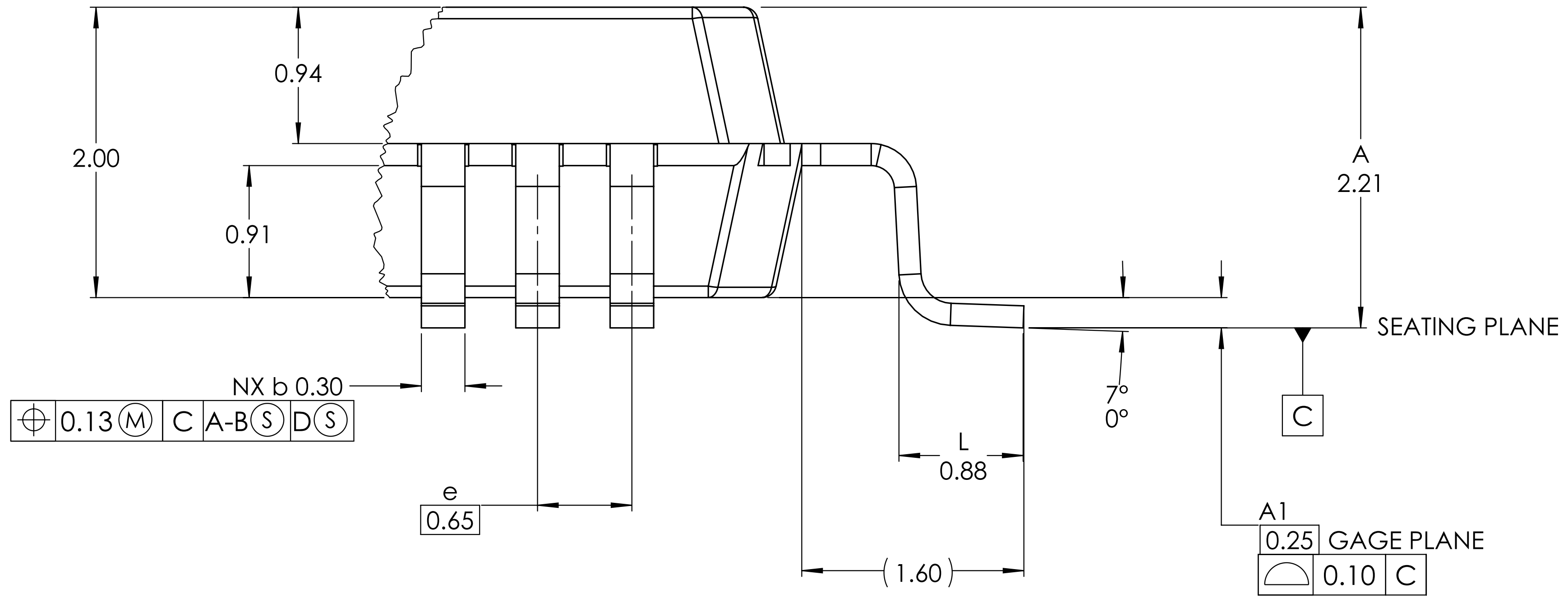
REVISIONS					
ECN	ZONE	REV.	DESCRIPTION	DATE	APPROVED
		A	ORIGINAL RELEASE	1/26/2023	SS
23-002	D4	B	ADDED 0.10 RADII TO MOLDED EDGES	2/17/2023	SS











DETAIL A
SCALE 25 : 1

SYMBOLS	MIN.	NOM.	MAX.
A	-	-	2.45
A1	0.00	-	0.25
A2	1.80	2.00	2.20
b	0.22	.30	0.36
D	13.20 BASIC		
D1	10.00 BASIC		
D2	7.80 REF		
E	13.20 BASIC		
E1	10.00 BASIC		
E2	7.80 REF		
e	0.65 BSC		
L	0.73	0.88	1.03
N	52		

GENERAL NOTES: (UNLESS OTHERWISE SPECIFIED)

1. PACKAGE OUTLINE PER JEDEC, MS-022, VARIATION AC.

2. MATERIALS:

   LEAD FRAME: EFTEC 64T 1/2 HARD WITH ADHESION ENHANCEMENT (A/E) THK = 0.152±0.008
   BODY: SUMITOMO EME-G770-HD EPOXY MOLDING COMPOUND.

3. LEAD FRAME FINISH: Ni/Pd/Au

   NICKEL: 0.50µ - 2.00µ (20µin - 79µin)
   PALLADIUM: 0.02µ - 0.15µ (0.79µin - 5.9µin)
   GOLD: 0.003µ - 0.015µ (0.12µin - 0.59µin)

4. DAP SIZE: 5.33mm

5. DAP PLATING OPTION: GROUND RING

PROPRIETARY AND CONFIDENTIAL

THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF QP TECHNOLOGIES, DIV. OF PROMEX IND. ANY REPRODUCTION IN PART, OR AS A WHOLE WITHOUT THE WRITTEN PERMISSION OF QP TECHNOLOGIES IS PROHIBITED.

NEXT ASSY	USED ON	MATERIAL SEE NOTE 2	
APPLICATION		FINISH SEE NOTE 3	

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
ALLOWABLE TOLERANCE LIMITS ARE SHOWN IN TABLE
THIRD ANGLE PROJECTION

	NAME	DATE
DRAWN	S. Swen	1/26/23
CHECKED	S. Swen	1/26/23
ENG APPR.	S. Swen	1/26/23

COMMENTS:

QPTECHNOLOGIES
A DIVISION OF PROMEX INDUSTRIES | QPTECHNOLOGIES.COM

TITLE:
10X10-52 LD, MQFP,
0.65 PITCH

SIZE	DWG. NO.	REV
D	501759	B
SCALE: 10:1	WEIGHT:	SHEET 1 OF 1